

**QUADRUPLE 2-INPUT POSITIVE-NAND GATES WITH OPEN-COLLECTOR OUTPUTS**

APRIL 1985 — REVISED MARCH 1988

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

**description**

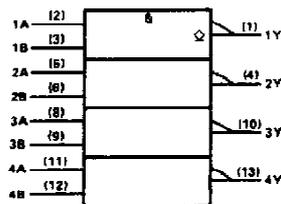
These devices contain four independent 2-input NAND gates. The open-collector outputs require pull-up resistors to perform correctly. They may be connected to other open-collector outputs to implement active-low wired-OR or active-high wired-AND functions. Open-collector devices are often used to generate higher  $V_{OH}$  levels.

The SN5401 and SN54LS01 are characterized for operation over the full military temperature range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ . The SN7401 and SN74LS01 are characterized for operation from  $0^{\circ}\text{C}$  to  $70^{\circ}\text{C}$ .

**FUNCTION TABLE (each gate)**

INPUTS		OUTPUT
A	B	Y
H	H	L
L	X	H
X	L	H

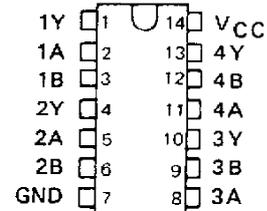
**logic symbol†**



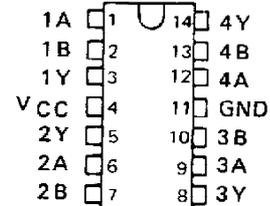
†This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

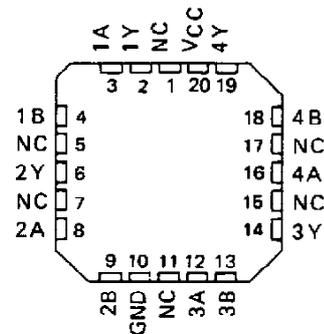
SN5401 . . . J PACKAGE  
SN54LS01 . . . J OR W PACKAGE  
SN7401 . . . N PACKAGE  
SN74LS01 . . . D OR N PACKAGE  
(TOP VIEW)



SN5401 . . . W PACKAGE  
(TOP VIEW)



SN54LS01 . . . FK PACKAGE  
(TOP VIEW)



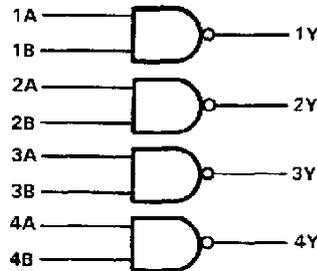
NC - No internal connection

PRODUCTION DATA documents contain information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



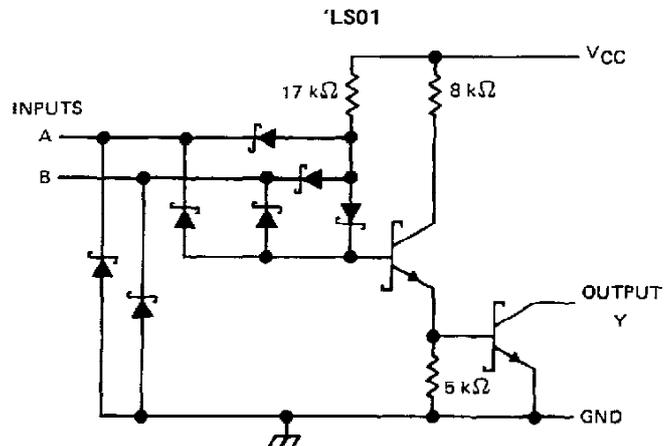
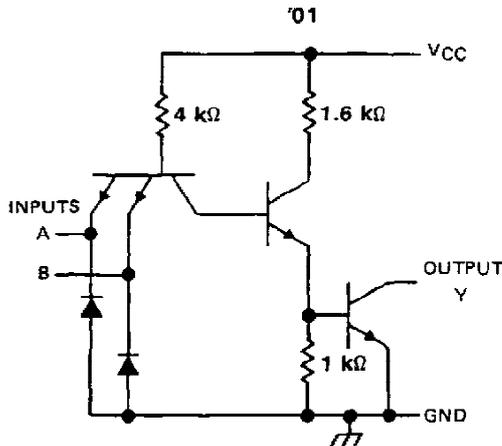
**SN5401, SN54LS01,  
SN7401, SN74LS01  
QUADRUPLE 2-INPUT POSITIVE-NAND GATES WITH OPEN-COLLECTOR OUTPUTS**

logic diagram (positive logic)



positive logic:  $Y = \overline{A \cdot B}$  or  $Y = \overline{A} + \overline{B}$

schematics (each gate)



Resistor values shown are nominal.

**absolute maximum ratings over operating free-air temperature range (unless otherwise noted)**

Supply voltage, $V_{CC}$ (see Note 1): '01, 'LS01	7 V
Input voltage: '01	5.5 V
'LS01	7 V
Off-state output voltage	7 V
Operating free-air temperature range: SN54'	-55°C to 125°C
SN74'	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminals.

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**SN5401, SN7401**  
**QUADRUPLE 2-INPUT POSITIVE-NAND GATES WITH OPEN-COLLECTOR OUTPUTS**

**recommended operating conditions**

	SN5401			SN7401			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub> Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V <sub>IH</sub> High-level input voltage	2			2			V
V <sub>IL</sub> Low-level input voltage	0.8			0.8			V
V <sub>OH</sub> High-level output voltage	5.5			5.5			V
I <sub>OL</sub> Low-level output current	16			16			mA
T <sub>A</sub> Operating free-air temperature	- 55      125			0      70			°C

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS†	SN5401			SN7401			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V <sub>IK</sub>	V <sub>CC</sub> = MIN, I <sub>I</sub> = -12 mA	-1.5			-1.5			V
I <sub>OH</sub>	V <sub>CC</sub> = MIN, V <sub>IL</sub> = 0.8 V, V <sub>OH</sub> = 5.5 V				0.25			mA
	V <sub>CC</sub> = MIN, V <sub>IL</sub> = 0.7 V, V <sub>OH</sub> = 5.5 V	0.25						
V <sub>OL</sub>	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, I <sub>OL</sub> = 16 mA	0.2	0.4		0.2	0.4	V	
I <sub>I</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 5.5 V	1			1			mA
I <sub>IH</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.4 V	40			40			μA
I <sub>IL</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.4 V	-1.6			-1.6			mA
I <sub>CCH</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0	4	8		4	8	mA	
I <sub>CCL</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 4.5 V	12	22		12	22	mA	

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

**switching characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C (see note 2)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		MIN	TYP	MAX	UNIT
t <sub>PLH</sub>	A or B	Y	R <sub>L</sub> = 4 kΩ,	C <sub>L</sub> = 15 pF	35	55	ns	
t <sub>PHL</sub>			R <sub>L</sub> = 400 Ω,	C <sub>L</sub> = 15 pF	8	15	ns	

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



# SN54LS01, SN74LS01

## QUADRUPLE 2-INPUT POSITIVE-NAND GATES WITH OPEN-COLLECTOR OUTPUTS

### recommended operating conditions

	SN54LS01			SN74LS01			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub> Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V <sub>IH</sub> High-level input voltage	2			2			V
V <sub>IL</sub> Low-level input voltage			0.7			0.8	V
V <sub>OH</sub> High-level output voltage			5.5			5.5	V
I <sub>OL</sub> Low-level output current			4			8	mA
T <sub>A</sub> Operating free-air temperature	-55		125	0		70	°C

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54LS01		SN74LS01		UNIT		
		MIN	TYP‡	MAX	MIN		TYP‡	MAX
V <sub>IK</sub>	V <sub>CC</sub> = MIN, I <sub>I</sub> = -18 mA			-1.5		-1.5	V	
I <sub>OH</sub>	V <sub>CC</sub> = MIN, V <sub>IL</sub> = MAX, V <sub>OH</sub> = 5.5 V			0.1		0.1	mA	
V <sub>OL</sub>	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, I <sub>OL</sub> = 4 mA		0.25	0.4		0.25	0.4	V
	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, I <sub>OL</sub> = 8 mA					0.35	0.5	
I <sub>I</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 7 V			0.1		0.1	mA	
I <sub>IH</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.7 V			20		20	μA	
I <sub>IL</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.4 V			-0.4		-0.4	mA	
I <sub>CCH</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0		0.8	1.6		0.8	1.6	mA
I <sub>CCL</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 4.5 V		2.4	4.4		2.4	4.4	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

### switching characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		MIN	TYP	MAX	UNIT
t <sub>PLH</sub>	A or B	Y	R <sub>L</sub> = 2 kΩ,	C <sub>L</sub> = 15 pF		17	32	ns
t <sub>PHL</sub>						15	28	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

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**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN5401J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS01J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS01J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN7401N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7401N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7401N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7401N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS01D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74LS01D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74LS01DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74LS01DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74LS01N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS01N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS01N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS01N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SNJ5401J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ5401J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ5401W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ5401W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS01FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
SNJ54LS01FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
SNJ54LS01J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS01J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS01W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS01W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

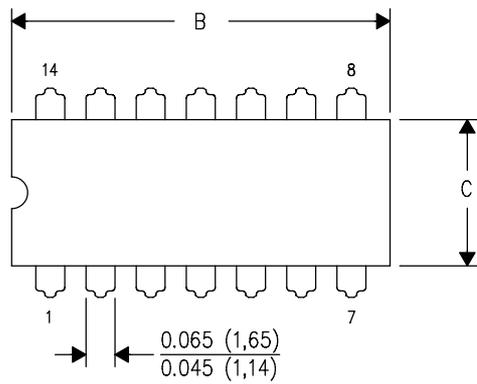
<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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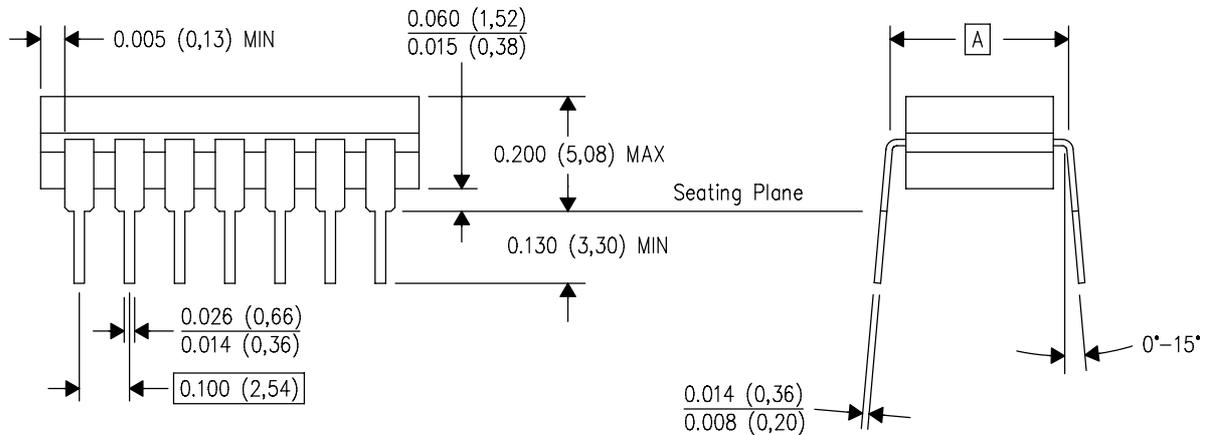
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J (R-GDIP-T\*\*)  
14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



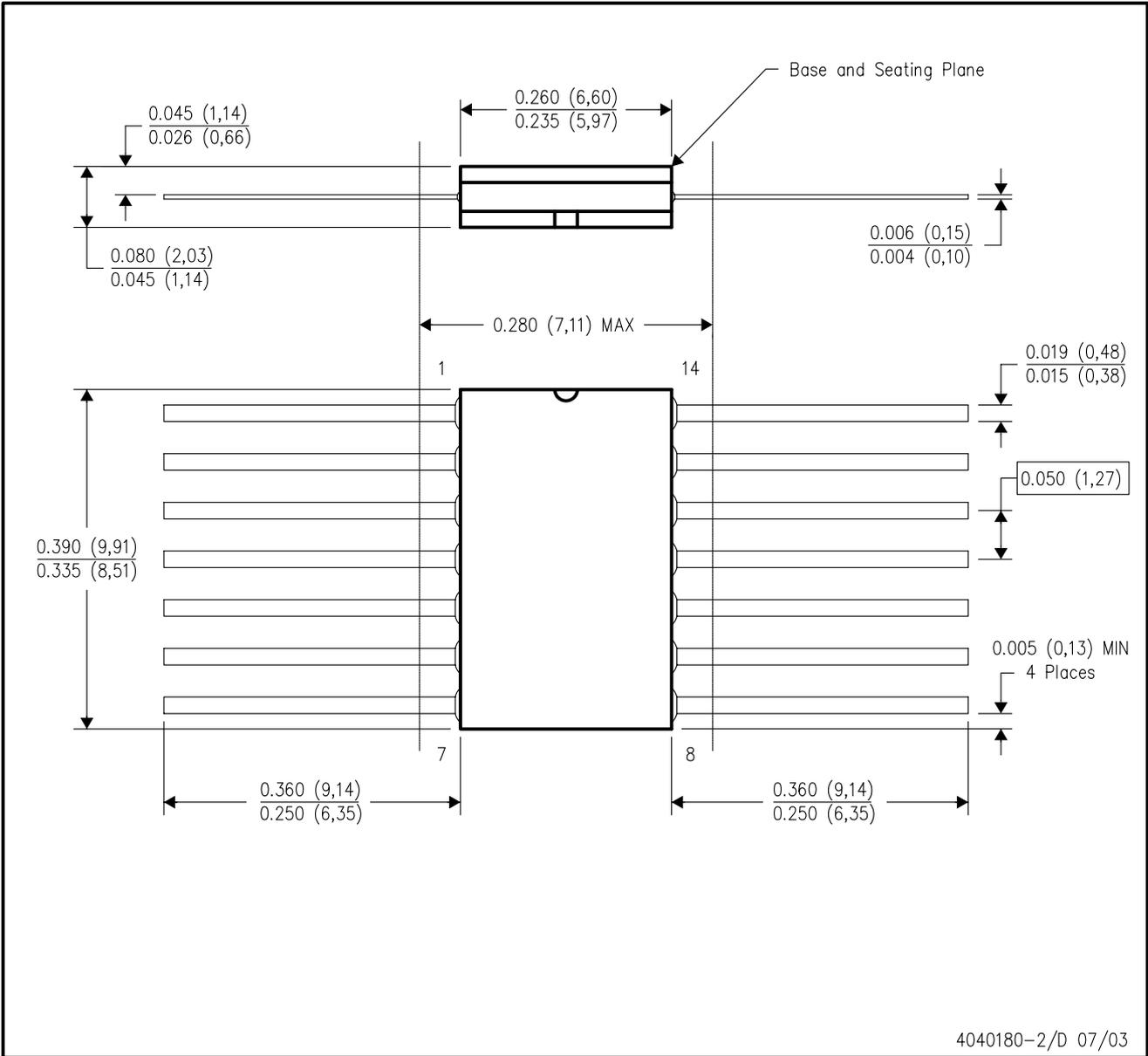
4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

MECHANICAL DATA

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK

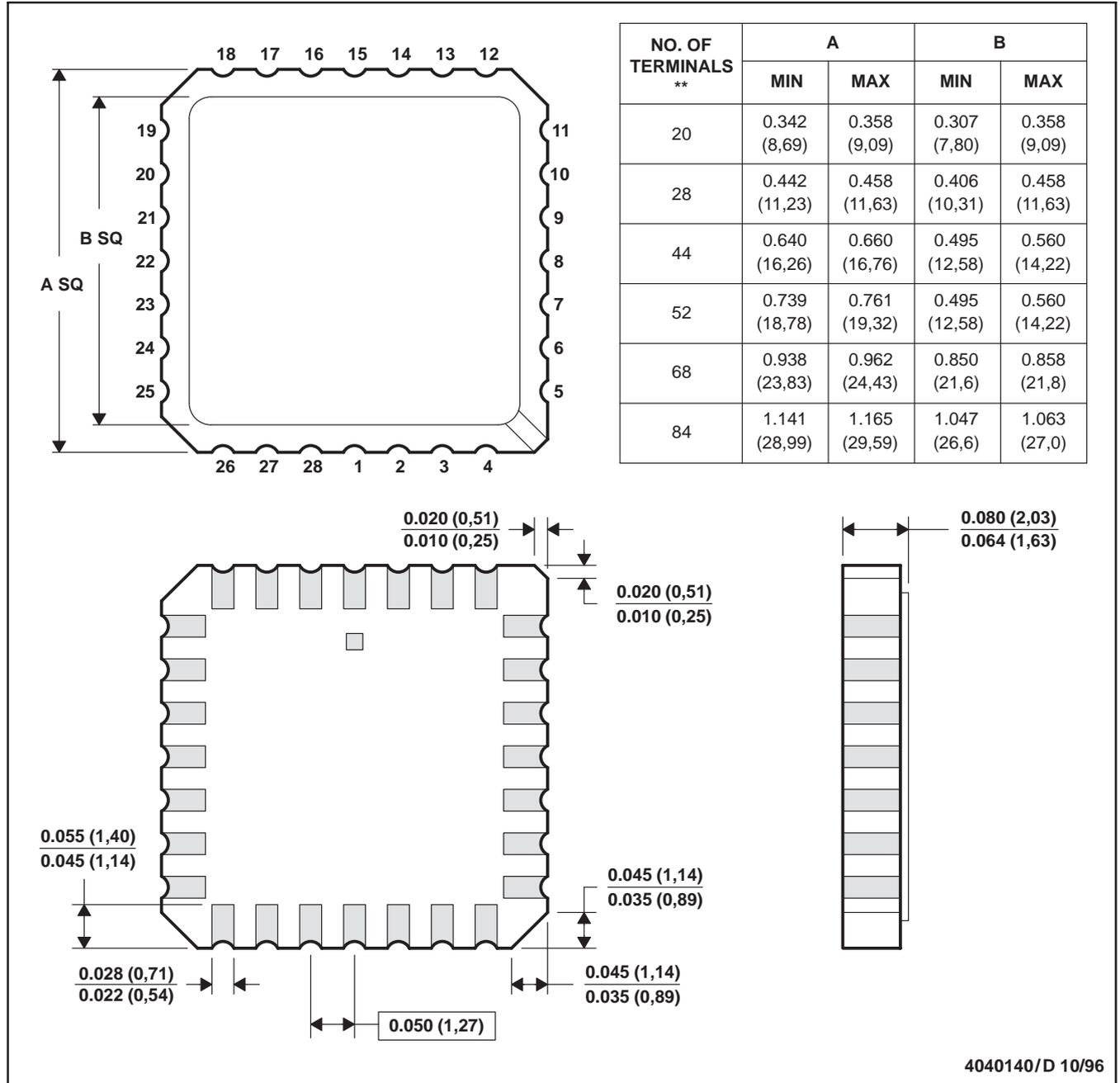


- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



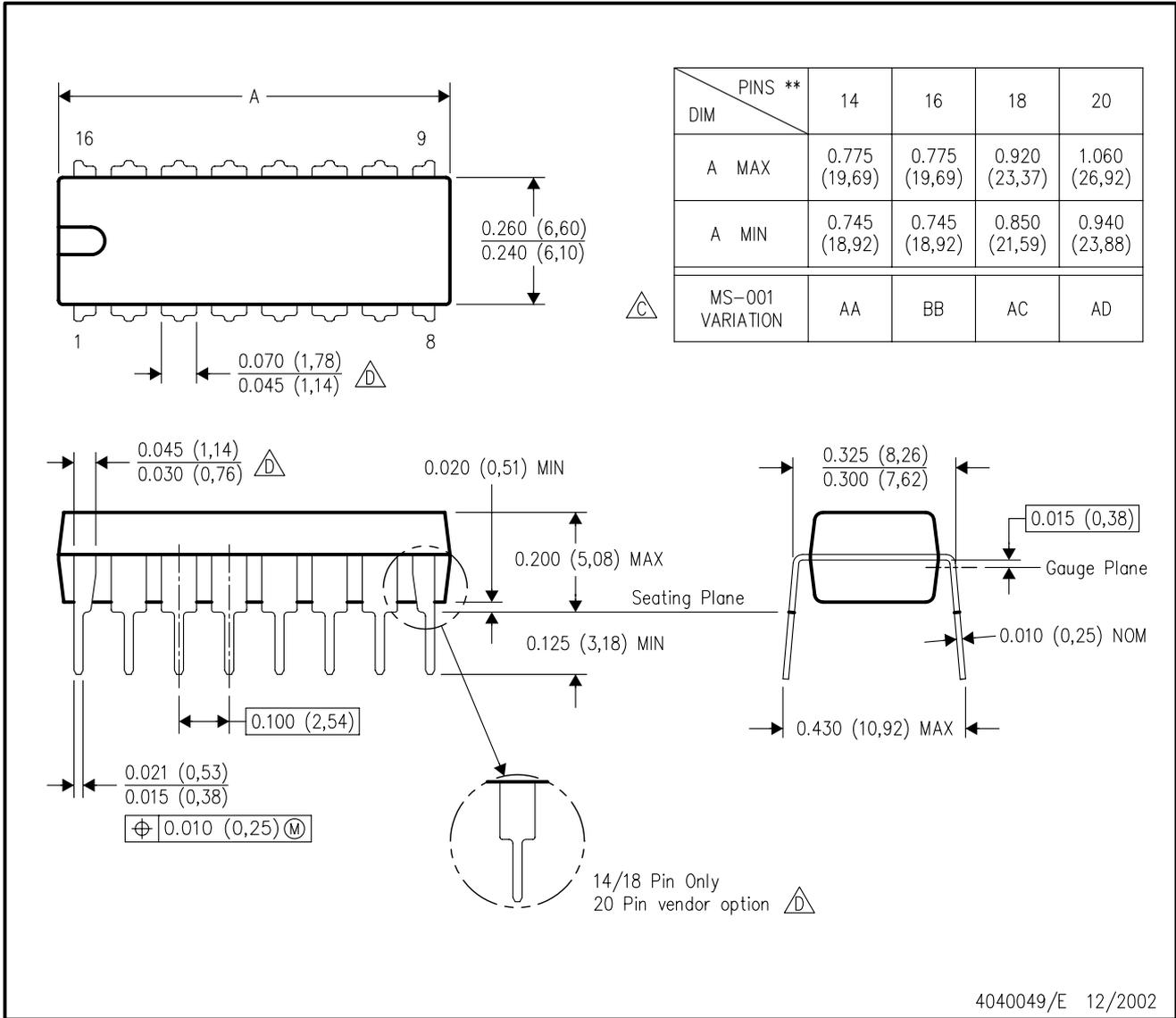
- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a metal lid.
  - D. The terminals are gold plated.
  - E. Falls within JEDEC MS-004

# MECHANICAL DATA

## N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

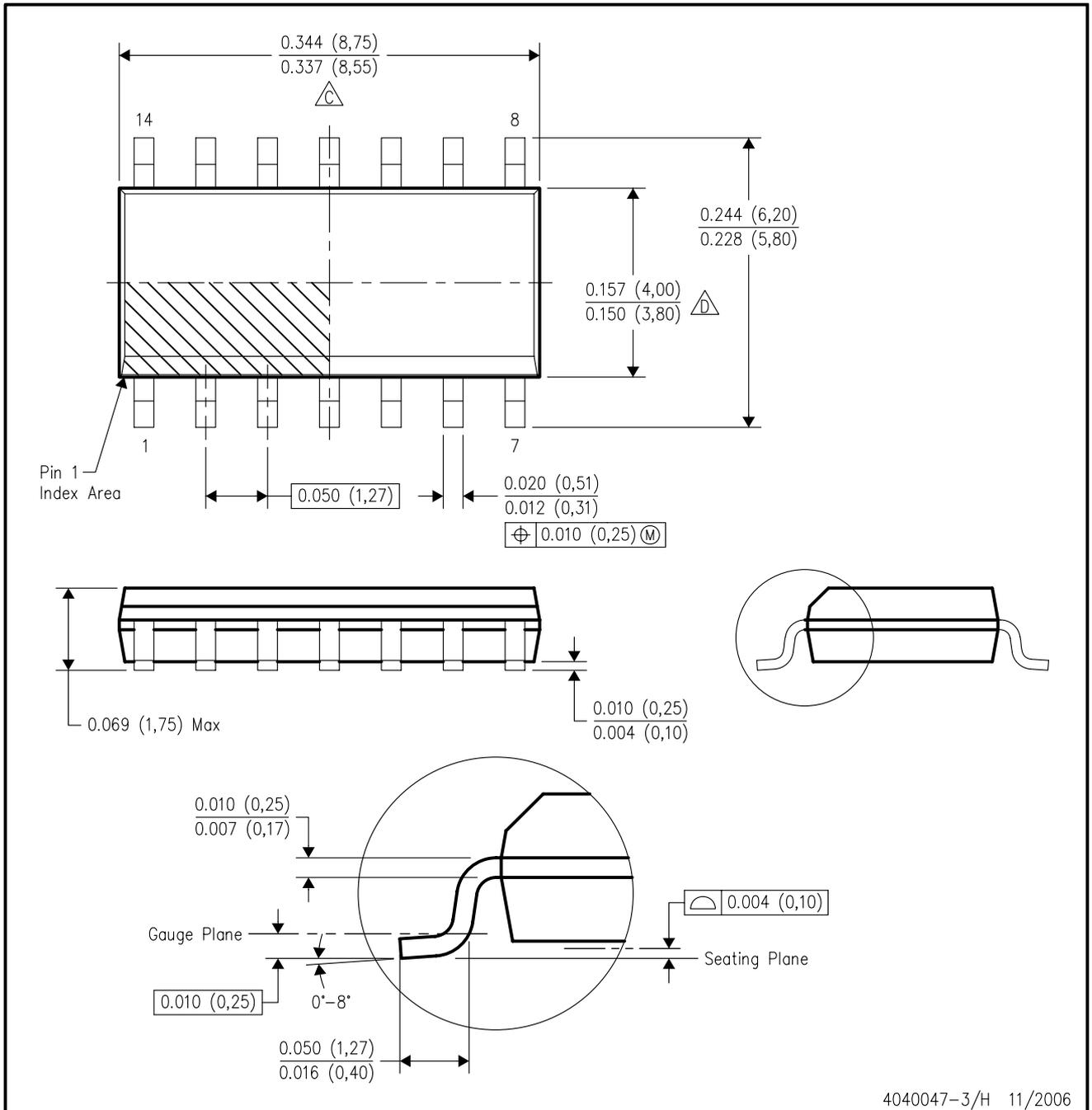


- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

# MECHANICAL DATA

## D (R-PDSO-G14)

## PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
  - Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
  - Reference JEDEC MS-012 variation AB.

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DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>	Broadband	<a href="http://www.ti.com/broadband">www.ti.com/broadband</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>	Digital Control	<a href="http://www.ti.com/digitalcontrol">www.ti.com/digitalcontrol</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>	Military	<a href="http://www.ti.com/military">www.ti.com/military</a>
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Low Power Wireless	<a href="http://www.ti.com/lpw">www.ti.com/lpw</a>	Telephony	<a href="http://www.ti.com/telephony">www.ti.com/telephony</a>
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